

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1 – 27. (canceled)

28. (new) A system comprising

- (a) a plurality of bonders for bonding semiconductor chips; each bonder having a calculating unit for manipulating data relating to a bonding operation, a memory unit for storing information relating to the bonding operation, an optical unit for acquiring visual images relating to the bonding operation, and an adaptive compensator for controlling the bonding operation;
- (b) a communication means for providing communication between the calculating unit, the memory unit, and the optical unit of a bonder, and for providing communication among bonders;
- (c) a semiconductor chip having a plurality of bondpads arranged on the semiconductor chip;
- (d) a set of group-segments for grouping the plurality of bondpads of the semiconductor chip, each segment having a reference member related to the bondpads in the segment;
- (e) a device program including information related to the semiconductor chip and the segments, stored in the memory unit of the bonders;
- (f) a visual-image file containing visual information of the segments acquired from the optical unit, stored in the memory unit of the bonder;
- (g) corrective data generated in the calculating unit relating the device program and the visual information; and
- (h) the adaptive compensator adaptive to receive the corrective data for controlling the bonding operation.

29. (new) A method for bonding a semiconductor chips with a plurality of bonders; comprising

- (a) providing a plurality of bonders; each bonder having a calculating unit for manipulating data relating to a bonding operation, a memory unit for storing information relating to the bonding operation, an optical unit for acquiring visual images relating to the bonding operation, and an adaptive compensator for controlling the bonding operation;
- (b) providing a communication means for providing communication between the calculating unit, the memory unit, and the optical unit of a bonder, and for providing communication among bonders;
- (c) providing a semiconductor chip having a plurality of bondpads arranged on the semiconductor chip;
- (d) grouping the plurality of bondpads of the semiconductor chip into a plurality of segments, each segment having a reference member related to the bondpads in the segment;
- (e) generating a device program including information related to the displacement of the bondpads on the semiconductor chip and related to the segments that group the bondpads;
- (f) storing the device program in the memory units of the bonders;
- (g) placing a semiconductor chip of the device program on a bonder having the device program;
- (h) capturing visual images of the segments of the bondpads on the semiconductor chip;
- (i) communicating the visual images to the calculating unit;
- (j) communicating the device program to the calculating unit;
- (k) generating corrective data in the calculating unit based on the device program and the visual images;

- (l) communicating the corrective data to the control unit for controlling the bonding operation; and
- (m) bonding the semiconductor chip based on the corrective data.